IN THE CLAIMS

1. (original) A method for measuring surface characteristics of a substrate having a repeating pattern of integrated circuits, the repeating pattern having a repeat dimension along a first axis, the method including the steps of:

defining an inspection grid of points on the substrate, the inspection grid of points having a spacing along the first axis,

directing an incident beam at the inspection grid of points on the substrate where the spacing of the points along the first axis is a submultiple of the repeat dimension of the repeating pattern along the first axis,

reflecting the incident beam off the substrate to produce a reflected beam,

receiving the reflected beam with a position sensitive detector,

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determining an actual landing location of the reflected beam on the position sensitive detector,

measuring a displacement between the actual landing location of the reflected beam from an expected landing location of the reflected beam on the position sensitive detector,

compiling a database of displacement measurements,

examining at least two displacement measurements in the database,

correcting at least one displacement measurement for effects of a pattern induced anomaly in the displacement measurements and producing an adjusted database, and

deriving the surface characteristics of the substrate from the adjusted database.

- 2. (original) The method of claim 1 wherein the step of correcting at least one displacement measurement for effects of a pattern induced anomaly in the displacement measurements comprises deriving a tilt at a point and subtracting the tilt at that point from the tilt at a comparable point in an adjoining pattern.
- 3. (original) The method of claim 1 wherein the step of directing an incident beam at the inspection grid of points on the substrate comprises adjusting the incident

beam with a collimating lens such that incident rays are substantially parallel for at least two points on the inspection grid.

- 4. (original) The method of claim 1 wherein the incident beam is comprised of more than one wavelength.
- 5. (original) The method of claim 1 wherein the incident beam is multiplexed between two wavelengths.
- 6. (original) The method of claim 1 wherein the method for directing the incident beam between points on the substrate comprises redirection by a galvo driven mirror.
- 7. (original) The method of claim 1 wherein the method for directing the incident beam between points on the substrate comprises redirection by an acousto optic modulator.
- 8. (original) The method of claim 1 wherein the position sensitive detector is a current sharing detector.
- 9. (currently amended) A method for measuring a topography of a substrate, the method comprising the steps of:
 - directing an incident beam at an inspection grid of points on the substrate where the points are selected so that a reflected beam from each point in the inspection grid has minimal distortion, wherein the incident beam is comprised of more than one wavelength,

receiving the reflected beam with a position sensitive detector,

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- measuring displacements between actual landing locations of the reflected beam and expected landing locations,
- deriving the topography of the substrate from the displacement measurements.
 - 10. (original) The method of claim 9 wherein the step of directing an incident beam at the inspection grid of points on the substrate comprises using a collimating lens

such that incident beams are substantially parallel for at least two points on the inspection grid.

11. (canceled).

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- 12. (original) The method of claim 9 wherein the incident beam is multiplexed between two wavelengths.
- 13. (original) The method of claim 9 wherein the method for directing the incident beam between the points on the substrate comprises redirection by a galvo driven mirror.
- 14. (original) The method of claim 9 wherein the method for directing the incident beam between the points on the substrate comprises redirection by an acousto optic modulator.
- 15. (original) The method of claim 9 wherein the position sensitive detector is a current sharing detector.
- 16. (original) An apparatus for detecting a characteristic of a substrate having a repeating pattern, the apparatus comprising:
 - a beam generator adapted to produce an incident beam along a path,
 - a scanner adapted to direct the path of the incident beam onto a substrate such that the incident beam strikes the substrate at inspection points on an inspection grid where a spacing of the inspection points along a first axis of the inspection grid is a submultiple of a repeat dimension of the repeating pattern on the substrate along the first axis, thereby producing a reflected beam,
- a modulator adapted to cause the incident beam to strike the substrate when the incident beam is directed at one of the inspection points,
 - a position sensitive detector adapted to produce an electronic signal representing a displacement measurement between an actual landing location of the reflected beam on the position sensitive detector and an expected landing location of the reflected beam on the position sensitive detector,

- (original) The apparatus of claim 16 further comprising a collimating lens adapted 17. to intercept the incident beam after it passes from the scanner and before the incident beam strikes the substrate.
- 18. (original) The apparatus of claim 16 wherein the incident beam is comprised of more than one wavelength.
- 19. (original) The apparatus of claim 16 wherein the incident beam is multiplexed between two wavelengths.
- 20. (original) The apparatus of claim 16 wherein the position sensitive detector is a current sharing detector.